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(54) Title: EPOXY RESIN FORMULATIONS

(57) Abstract: A curable halogen-free epoxy resin composition comprising from 40 to 80 percent by weight of a phenol aldehyde condensation product, from 10 to 40 percent by weight of a phosphorous-containing phenolic epoxy resin, and from 10 to 40 percent by weight of an aromatic hardening agent having a sulphone group and an amine group. A prepreg and laminate can be formed from this composition.

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